



CERTIFICATE

The Certification Body
of TÜV SÜD PSB Pte Ltd

certifies that

STATS CHIPPAC LTD

5 Yishun Street 23
Singapore 768442

has established and applies
a Quality Management System for

- 1) Design and Development of ICs Package and Test Hardware & Software
- 2) Wafer Sort, Assembly and Test of ICs
- 3) Wafer Process (Bump and Integrated Passive Devices) and Wafer Level Chip Scale Packages (WLCSP)
(see Appendix to Certificate for Details)

Proof has been furnished that the requirements
according to

ISO 9001 : 2000

are fulfilled. The certificate is valid from 2007-07-18 to 2010-07-17

Certificate Registration No. 96-2-0622

Date of Issue : 2007-08-03



Tek Ming WU



ZERTIFIKAT ♦ CERTIFICATE ♦ 認証證書 ♦ CERTIFICADO ♦ CERTIFICAT



APPENDIX

To Certificate Number: 96-2-0622

Issue Number : 1

Date of Issue: 2007-08-03

Issued to: STATS ChipPac Ltd
5 Yishun Street 23
Singapore 768442

Process or service in respect of which the company is Certified:

- 1) Design and Development of ICs Package and Test Hardware & Software
- 2) Wafer Sort, Assembly and Test of ICs
- 3) Wafer Process (Bump and Integrated Passive Devices) and Wafer Level Chip Scale Packages (WLCSP)

Process Detail(s)/Location(s):

- 1) Activities like CEO office, Demand and Solutions Management, Pricing Management (PM), Technology Development (TD), Management of training for TD staff are located at 10 Ang Mo Kio Street 65, Techpoint, #05-17/20, Singapore 569059
- 2) Additional Production sites are located at :
 - (a) STATS ChipPAC Test Services, Inc
1768 McCandless Drive,
Milpitas, CA 95035, USA
 - (b) STATS ChipPAC Test Services, Inc
9868 Scranton Road, Suite 1221
San Diego, CA 92121, USA



Tek Ming WU
TÜV SÜD PSB Pte Ltd

